

PROTECTIVE TAPE APPLYING AND
SEPARATING METHOD

ABSTRACT OF THE DISCLOSURE

A protective tape is applied by a tape applying mechanism to a surface of a wafer suction-supported by a chuck table. The protective tape is cut to the shape of the
5 wafer by a cutter unit. Then, a protective tape having stronger adhesion than the first protective tape is applied over the protective tape. The protective tapes in plies are separated together from the surface of the wafer in one separating operation of a tape separating device.

Fig. 7



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